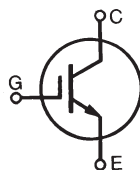


# High Voltage IGBT

# IXGL75N250

For Capacitor Discharge Applications

( Electrically Isolated Tab )



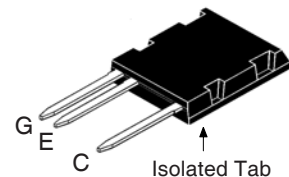
$$V_{CES} = 2500V$$

$$I_{C90} = 65A$$

$$V_{CE(sat)} \leq 2.9V$$

Symbol	Test Conditions	Maximum Ratings	
$V_{CES}$	$T_J = 25^\circ C$ to $150^\circ C$	2500	V
$V_{CES}$	$T_J = 25^\circ C$ to $150^\circ C$ , $R_{GE} = 1M\Omega$	2500	V
$V_{GES}$	Continuous	$\pm 20$	V
$V_{GEM}$	Transient	$\pm 30$	V
$I_{C25}$	$T_C = 25^\circ C$	110	A
$I_{C90}$	$T_C = 90^\circ C$	65	A
$I_{CM}$	$T_C = 25^\circ C$ , $V_{GE} = 20V$ , 1ms	580	A
<b>SSOA</b>	$V_{GE} = 15V$ , $T_{VJ} = 125^\circ C$ , $R_G = 1\Omega$	$I_{CM} = 200$	A
<b>(RBSOA)</b>	Clamped Inductive Load	$V_{CE} \leq 0.8 \cdot V_{CES}$	
$P_C$	$T_C = 25^\circ C$	430	W
$T_J$		-55 ... +150	$^\circ C$
$T_{JM}$		150	$^\circ C$
$T_{stg}$		-55 ... +150	$^\circ C$
$T_L$	Maximum Lead Temperature for Soldering	300	$^\circ C$
$T_{SOLD}$	1.6 mm (0.062 in.) from Case for 10s	260	$^\circ C$
$V_{ISOL}$	50/60Hz, 1 minute	2500	V~
$F_C$	Mounting Force with Clip	30..170 / 7..36	Nm/lb-in.
<b>Weight</b>		8	g

## ISOPLUS i5-Pak™



G = Gate      C = Collector  
E = Emitter

## Features

- Very High Peak Current Capability
- Low Saturation Voltage
- MOS Gate Turn-On
- Rugged NPT Structure
- ISOPLUS i5-PAK™ High Voltage Package
  - Isolated Back Surface
  - Enlarged Creepage Towards Heat-Sink
  - Enlarged Creepage between High Voltage Pins
  - Application Friendly PinOut
  - High Reliability
  - Industry Standard Outline
  - UL Registered

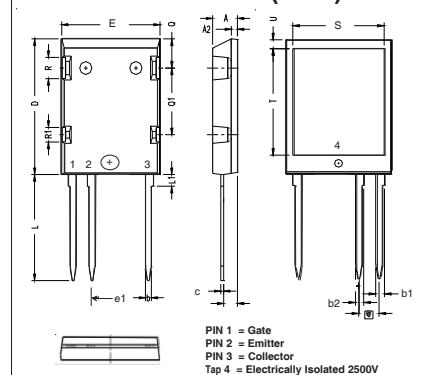
## Applications

- Capacitor Discharge
- Pulser Circuits

Symbol	Test Conditions ( $T_J = 25^\circ C$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$BV_{CES}$	$I_C = 1mA$ , $V_{GE} = 0V$	2500		V
$V_{GE(th)}$	$I_C = 4mA$ , $V_{CE} = V_{GE}$	3.0		5.0 V
$I_{CES}$	$V_{CE} = 0.8 \cdot V_{CES}$ , $V_{GE} = 0V$ Note 2, $T_J = 125^\circ C$			50 $\mu A$ 5 mA
$I_{GES}$	$V_{CE} = 0V$ , $V_{GE} = \pm 20V$			$\pm 200$ nA
$V_{CE(sat)}$	$I_C = 75A$ , $V_{GE} = 15V$ , Note 1		2.5	2.9 V
	$I_C = 300A$ , $V_{GE} = 25V$		4.1	V

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$g_{fs}$	$I_C = 60\text{A}$ , $V_{CE} = 10\text{V}$ , Note 1	35	58	S
$C_{ies}$	$V_{CE} = 25\text{V}$ , $V_{GE} = 0\text{V}$ , $f = 1\text{MHz}$		9000	pF
$C_{oes}$			345	pF
$C_{res}$			110	pF
$Q_g$	$I_C = 75\text{A}$ , $V_{GE} = 15\text{V}$ , $V_{CE} = 0.5 \cdot V_{CES}$		410	nC
$Q_{ge}$			63	nC
$Q_{gc}$			175	nC
$t_{d(on)}$	<b>Resistive Switching Times</b>		55	ns
$t_r$	$I_C = 150\text{A}$ , $V_{GE} = 15\text{V}$		225	ns
$t_{d(off)}$	$V_{CE} = 1250\text{V}$ , $R_G = 1\Omega$		270	ns
$t_f$			455	ns
$R_{thJC}$				$0.29^\circ\text{C/W}$
$R_{thCK}$		0.15		$^\circ\text{C/W}$

## ISOPLUS i5-Pak™ HV (IXGL) Outline



SYM	INCHES		MILLIMETER	
	MIN	MAX	MIN	MAX
A	0.190	0.205	4.83	5.21
A1	0.102	0.118	2.59	3.00
A2	0.046	0.055	1.17	1.40
b	0.045	0.055	1.14	1.40
b1	0.063	0.072	1.60	1.83
b2	0.058	0.068	1.47	1.73
c	0.020	0.029	0.51	0.74
D	1.020	1.040	25.91	26.42
E	0.770	0.799	19.56	20.29
e	0.150 BSC		3.81 BSC	
e1	0.450 BSC		11.43 BSC	
L	0.780	0.820	19.81	20.83
L1	0.080	0.102	2.03	2.59
Q	0.210	0.235	5.33	5.97
Q1	0.490	0.513	12.45	13.03
R	0.150	0.180	3.81	4.57
R1	0.100	0.130	2.54	3.30
S	0.668	0.690	16.97	17.53
T	0.801	0.821	20.34	20.85
U	0.065	0.080	1.65	2.03

### Notes:

1. Pulse test,  $t \leq 300\mu\text{s}$ , duty cycle,  $d \leq 2\%$ .
2. Part must be heatsunk for high-temp  $I_{ces}$  measurement.

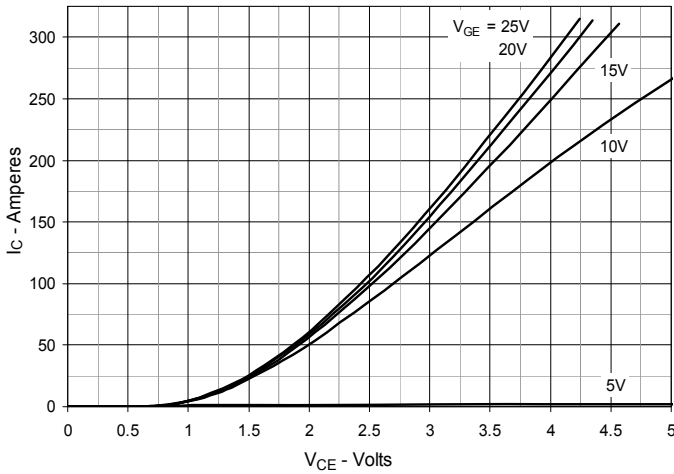
### PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

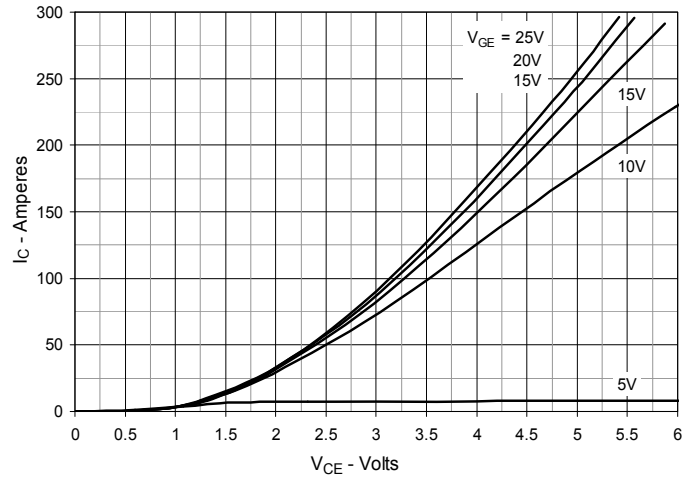
IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 7,005,734 B2 7,157,338B2  
4,850,072 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405 B2 6,759,692 7,063,975 B2  
4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2 7,071,537

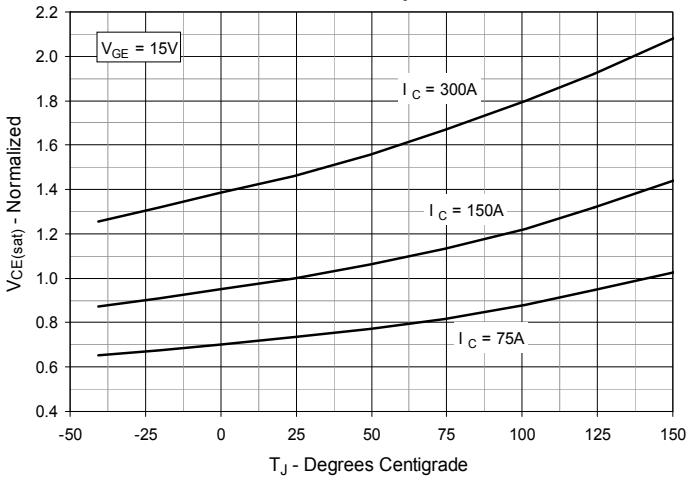
**Fig. 1. Output Characteristics @  $T_J = 25^\circ\text{C}$**



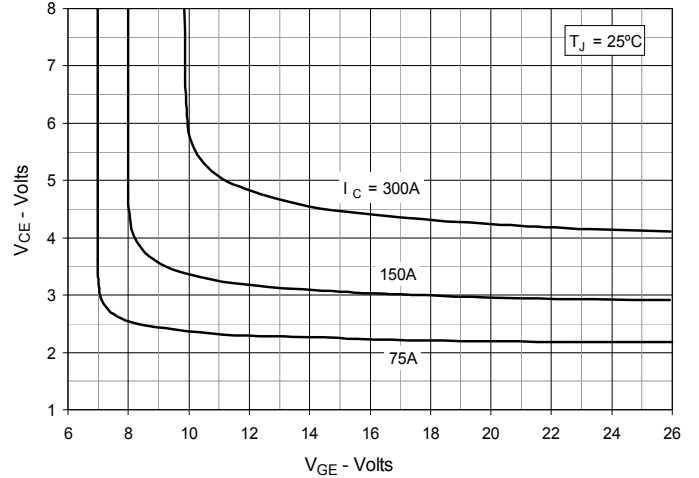
**Fig. 2. Output Characteristics @  $T_J = 125^\circ\text{C}$**



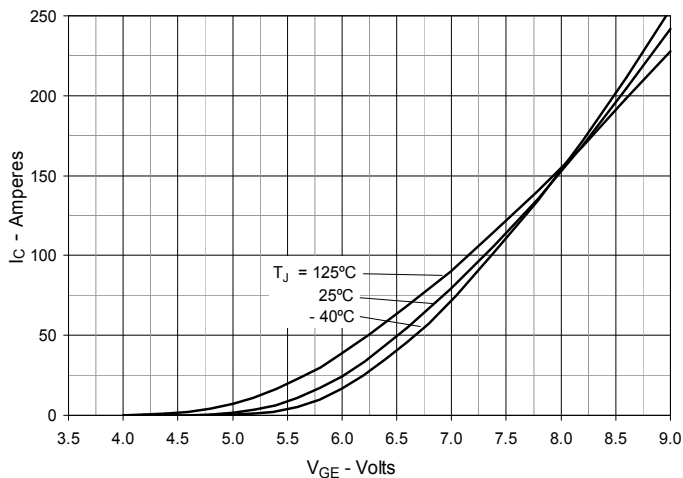
**Fig. 3. Dependence of  $V_{CE(sat)}$  on Junction Temperature**



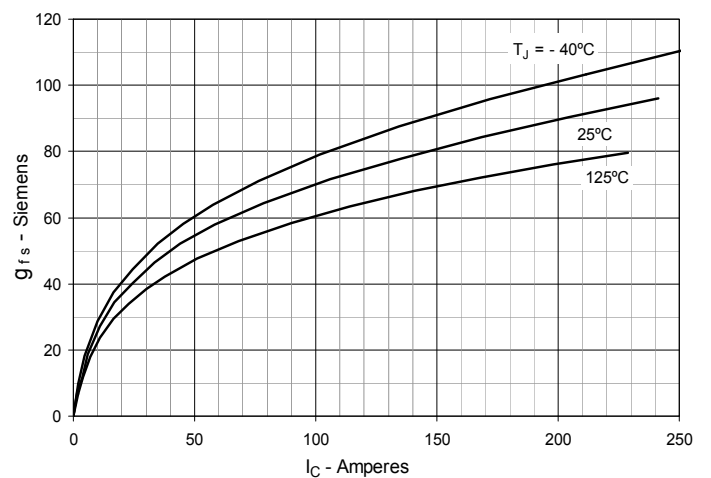
**Fig. 4. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage**



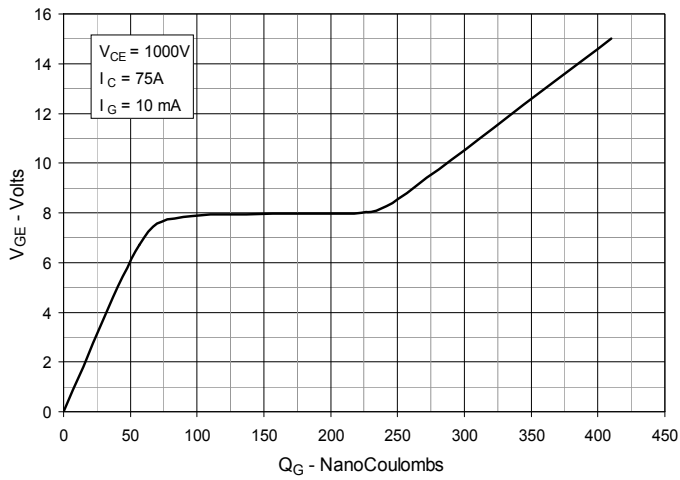
**Fig. 5. Input Admittance**



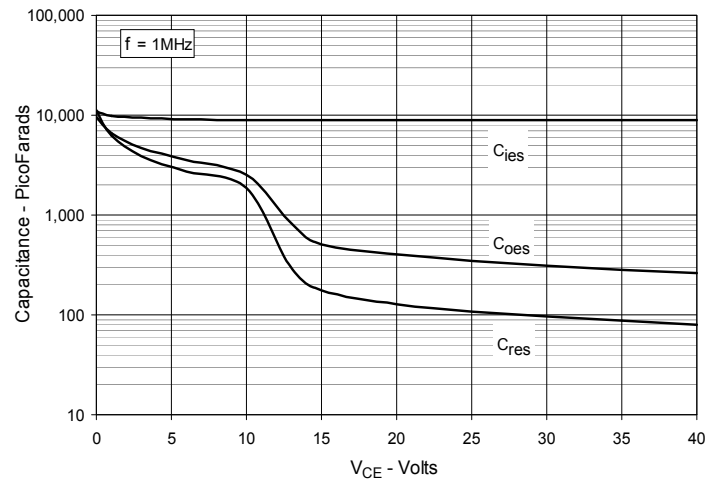
**Fig. 6. Transconductance**



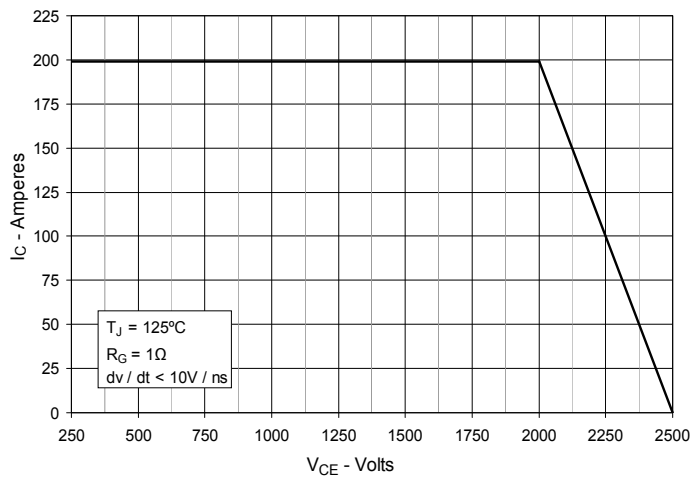
**Fig. 7. Gate Charge**



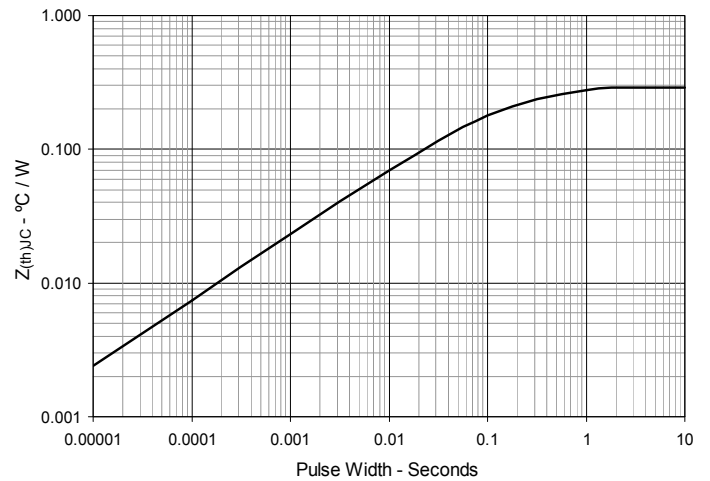
**Fig. 8. Capacitance**



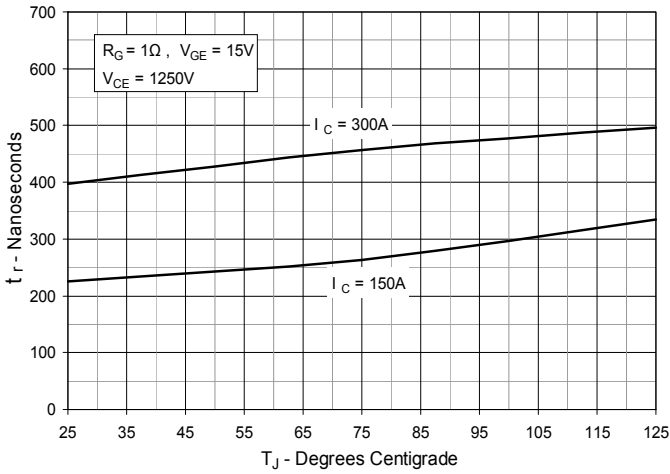
**Fig. 9. Reverse-Bias Safe Operating Area**



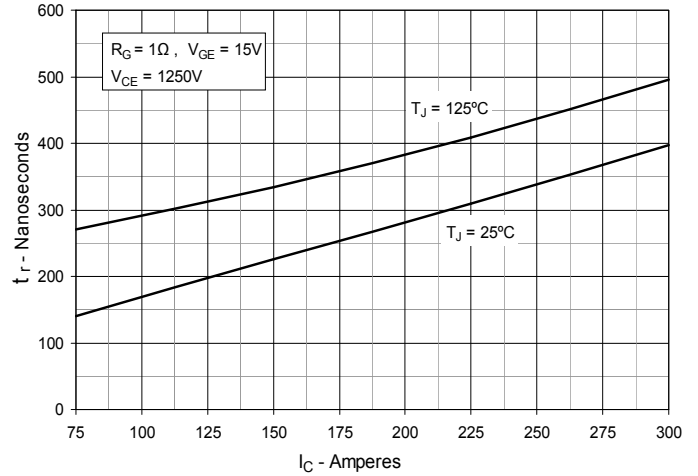
**Fig. 10. Maximum Transient Thermal Impedance**



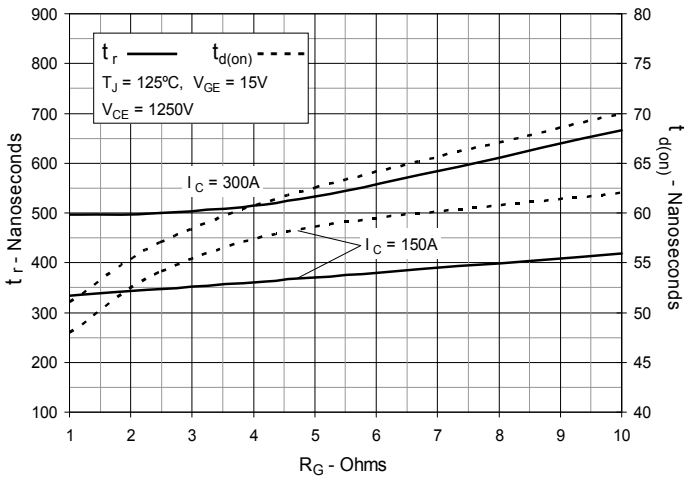
**Fig. 11. Resistive Turn-on Rise Time vs. Junction Temperature**



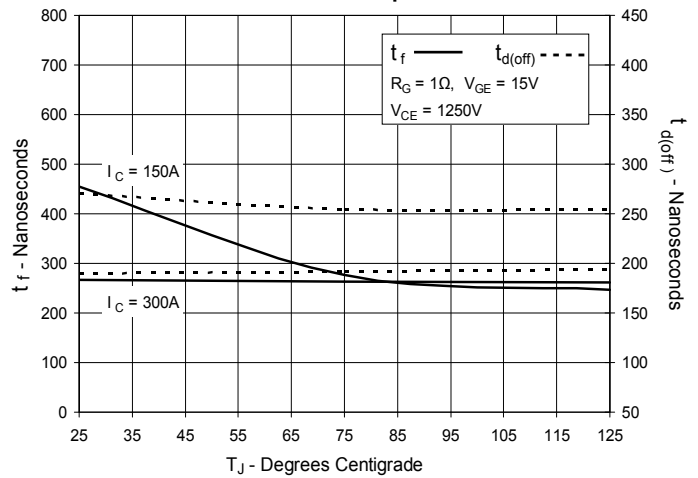
**Fig. 12. Resistive Turn-on Rise Time vs. Collector Current**



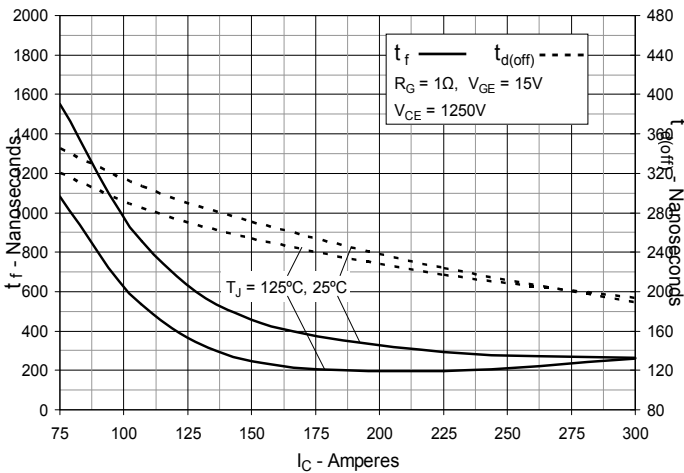
**Fig. 13. Resistive Turn-on Switching Times vs. Gate Resistance**



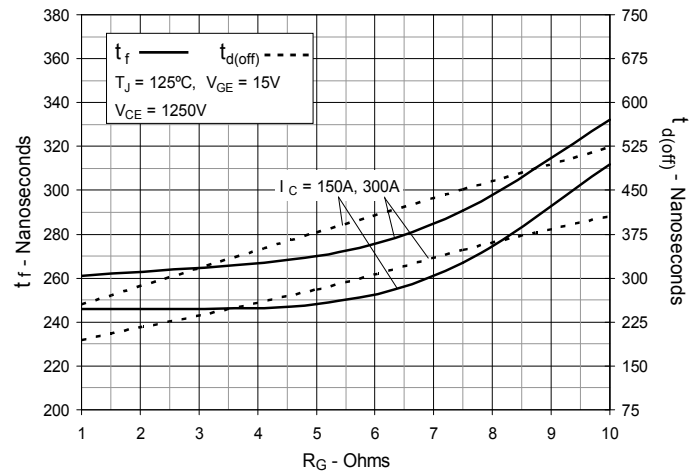
**Fig. 14. Resistive Turn-off Switching Times vs. Junction Temperature**



**Fig. 15. Resistive Turn-off Switching Times vs. Collector Current**



**Fig. 16. Resistive Turn-off Switching Times vs. Gate Resistance**





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